

Title (en)

CONNECTING THERMALLY-SPRAYED LAYER STRUCTURES OF HEATING DEVICES

Title (de)

VERBINDEN THERMISCH AUFGESPRITZTER SCHICHTSTRUKTUREN VON HEIZEINRICHTUNGEN

Title (fr)

LIAISON THERMIQUE DE STRUCTURES DE COUCHES PULVÉRISÉES DE DISPOSITIFS DE CHAUFFAGE

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Application

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Abstract (en)

[origin: WO2017021076A1] The invention relates to a heating device (1) for a domestic appliance (H), comprising a planar carrier (2) with a carrier surface (3), at least one layer structure (4-8) that is thermally sprayed onto said carrier surface (3), and at least one solder volume (9, 13a, 13b, 17, 18, 19) that is applied to at least one thermally-sprayed layer structure (4-8), wherein at least one solder volume is an ultrasonically-soldered solder volume (9, 13a, 7, 19). A domestic appliance (H) with a heating device comprises at least one heating device (1). A method is used to produce a heating device (1) for a domestic appliance (H), wherein a planar carrier (2) is provided which has at least one thermally-sprayed layer structure (4-8) applied thereto, and at least one solder volume (9, 3a, 17, 19) is ultrasonically soldered onto at least one thermally-sprayed layer structure (4-8). The invention is particularly advantageous for use with cooking appliances, particularly those having steam cooking capabilities, dishwashers, washing machines, laundry care appliances and small domestic appliances.

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